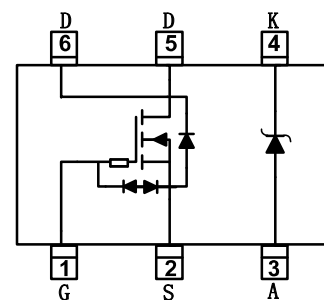
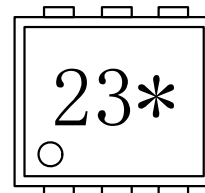


WNM2310
[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)
**Integrated N-Channel Power MOSFET
And Schottky Barrier Diode**

SOT-563B

MOSFET	
V _{DS} (V)	R _{ds(on)} (Ω)
20	0.380@ V _{GS} =4.5V
	0.520@ V _{GS} =2.5V
	0.735@ V _{GS} =1.8V
ESD Protected	
Schottky Barrier Diode	
V _R (V)	Typical V _F (V)
30	0.37@0.1A


Pin configuration (Top view)


23= Device Code

* = Month (A~Z)

Marking
Descriptions

The WNM2310 is N-Channel enhancement MOS Field Effect Transistor and Schottky Diode as a single package for switching. Uses advanced trench technology and design to provide excellent R_{DS (ON)} with low gate charge. Standard Product WNM2310 is Pb-free and Halogen-free.

Features

- Small package SOT-563B
- Featuring a MOSFET and Schottky Barrier Diode
- Excellent ON resistance for higher DC current
- Low leakage current Schottky Barrier Diode

Applications

- Driver: Relay, Solenoid, Lamps, Hammers etc.
- Power supply converters circuit
- Load/Power Switching for portable device

Order information

Device	Package	Shipping
WNM2310-6/TR	SOT-563B	10000/Reel&Tape

Absolute Maximum ratings (N-Channel, $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	10 S	Steady State	Unit
Drain-Source Voltage		V_{DS}	20		V
Gate-Source Voltage		V_{GS}	± 10		
Continuous Drain Current ^{a d}	$T_A=25^\circ\text{C}$	I_D	0.59	0.54	A
	$T_A=70^\circ\text{C}$		0.47	0.43	
Maximum Power Dissipation ^{a d}	$T_A=25^\circ\text{C}$	P_D	0.38	0.32	W
	$T_A=70^\circ\text{C}$		0.25	0.20	
Continuous Drain Current ^{b d}	$T_A=25^\circ\text{C}$	I_D	0.51	0.46	A
	$T_A=70^\circ\text{C}$		0.41	0.37	
Maximum Power Dissipation ^{b d}	$T_A=25^\circ\text{C}$	P_D	0.28	0.23	W
	$T_A=70^\circ\text{C}$		0.18	0.15	
Pulsed Drain Current ^c		I_{DM}	1.00		A
Operating Junction Temperature		T_J	-55 to 150		$^\circ\text{C}$
Lead Temperature		T_L	260		$^\circ\text{C}$
Storage Temperature Range		T_{stg}	-55 to 150		$^\circ\text{C}$

Absolute Maximum ratings (Schottky, $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Reverse Voltage (repetitive peak)	V_{RM}	30	V
Reverse Voltage (DC)	V_R	30	V
Average Rectified Forward Current	I_F	0.1	A
Peak Forward Surge Current (8.3ms single sine pluse)	I_{FSM}	0.5	A
Junction Temperature	T_J	-40 ~ 150	$^\circ\text{C}$
Operating Temperature	T_{opr}	-40 ~ 125	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 ~ 150	$^\circ\text{C}$

Thermal resistance ratings

Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance ^a	$t \leq 10 \text{ s}$	$R_{\theta JA}$	275	325	$^\circ\text{C/W}$
	Steady State		330	395	
Junction-to-Ambient Thermal Resistance ^b	$t \leq 10 \text{ s}$	$R_{\theta JA}$	375	440	
	Steady State		445	535	
Junction-to-Case Thermal Resistance		$R_{\theta JC}$	250	290	

a Surface mounted on FR-4 Board using 1 square inch pad size, 1oz copper

b Surface mounted on FR-4 board using minimum pad size, 1oz copper

c Pulse width < 380 μs , Duty Cycle < 2%

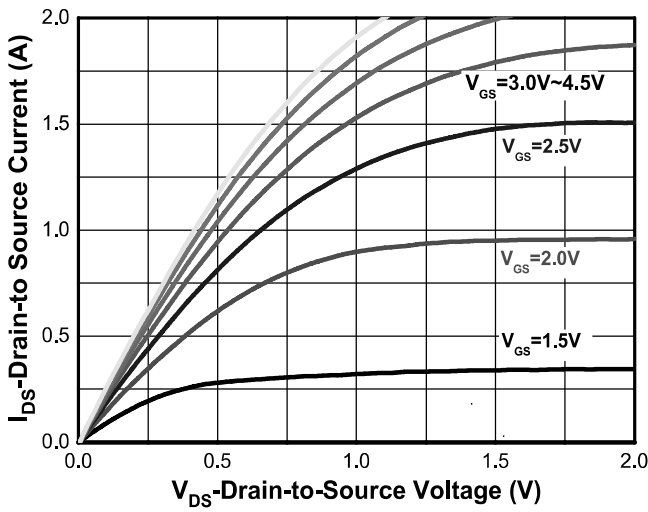
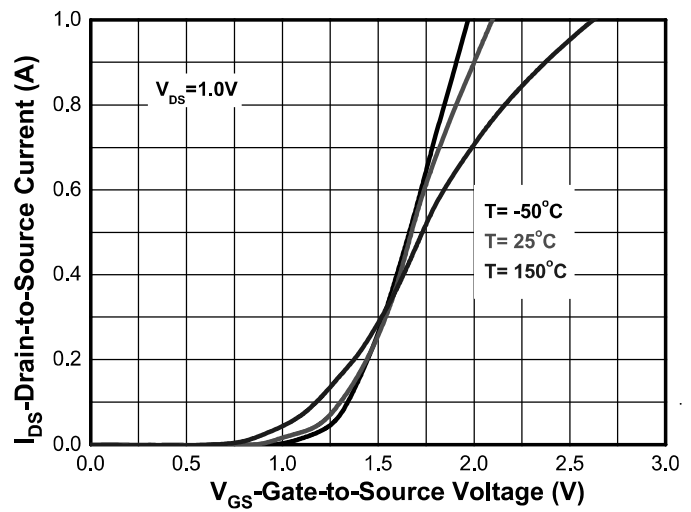
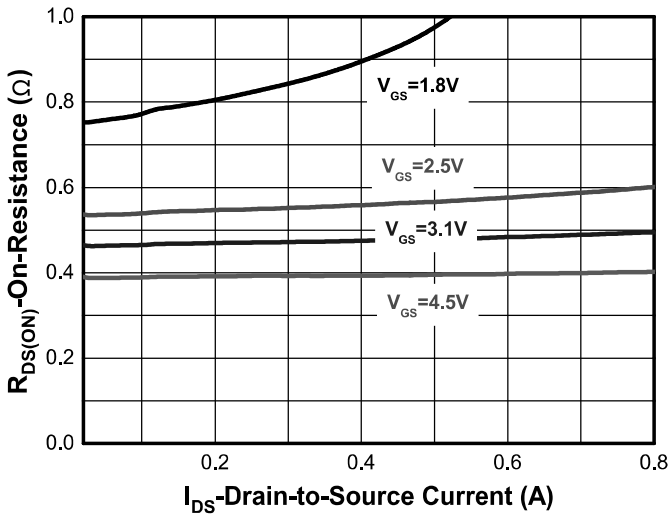
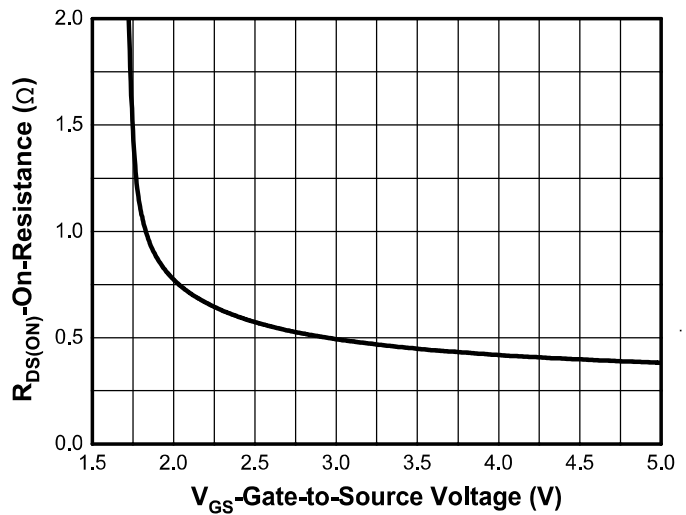
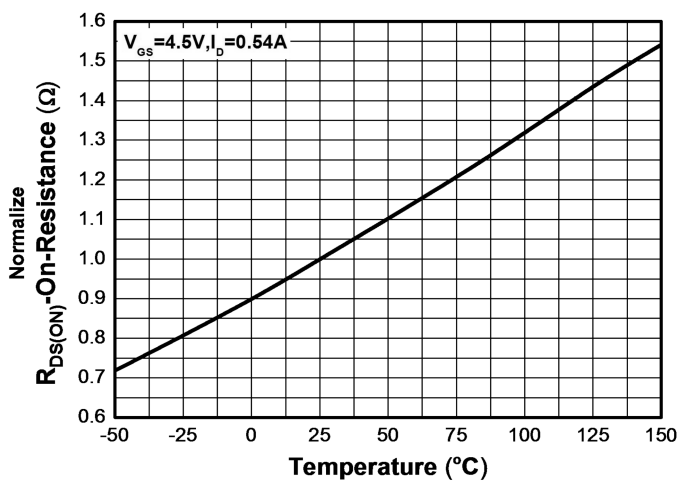
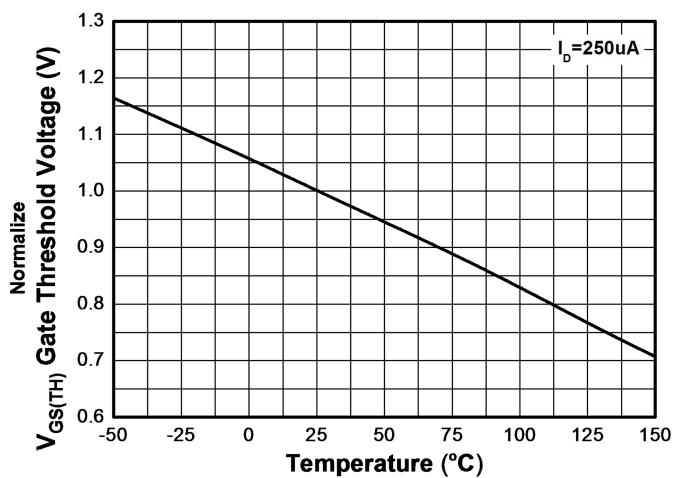
d Maximum junction temperature $T_J=150^\circ\text{C}$.

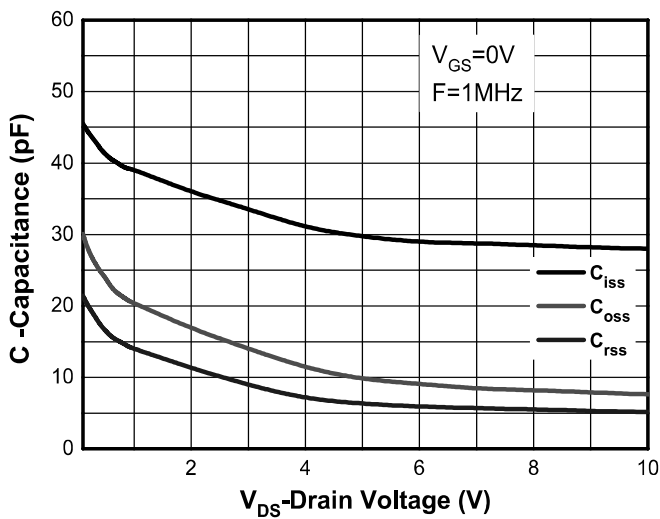
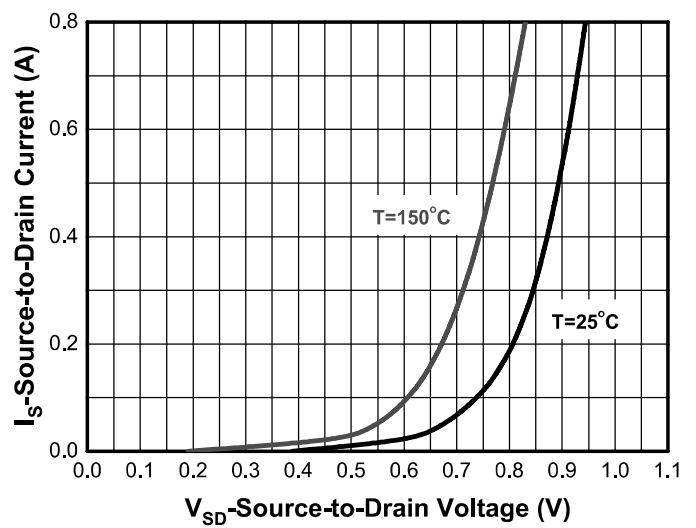
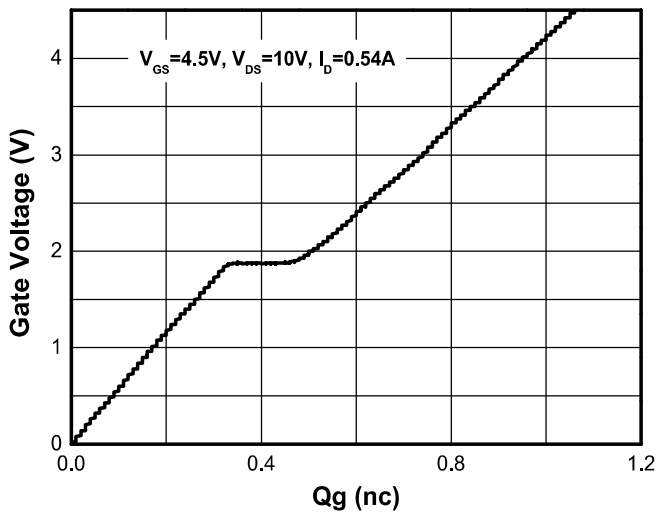
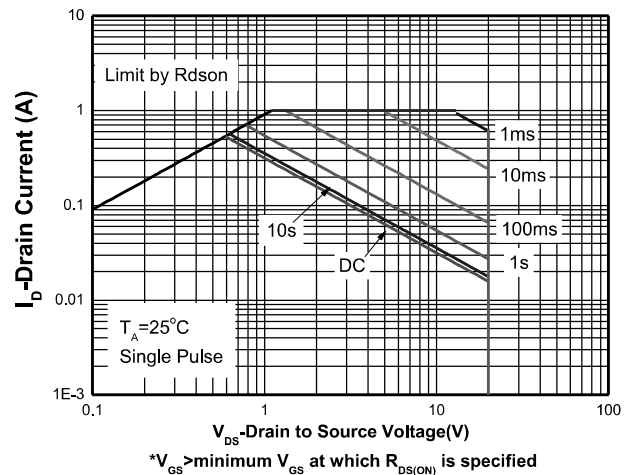
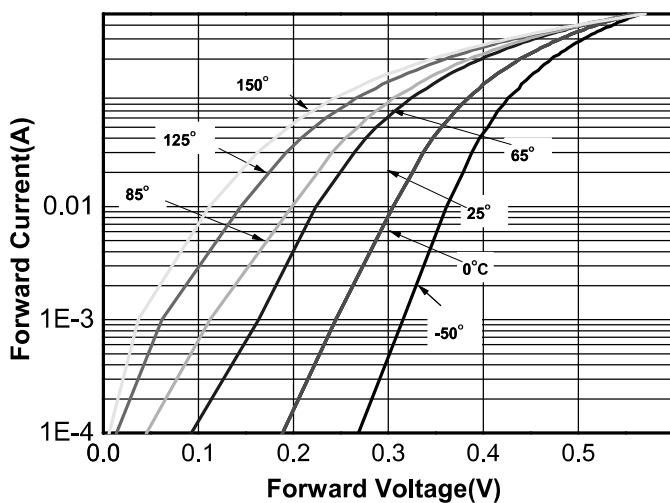
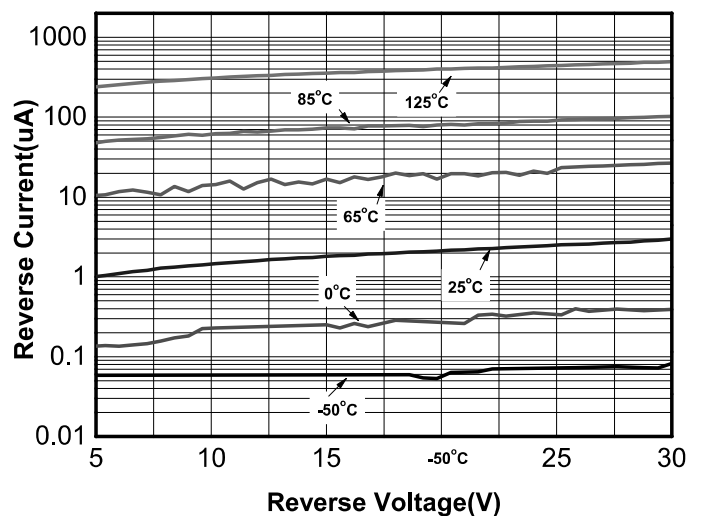
Electronics Characteristics (Ta=25°C, unless otherwise noted)

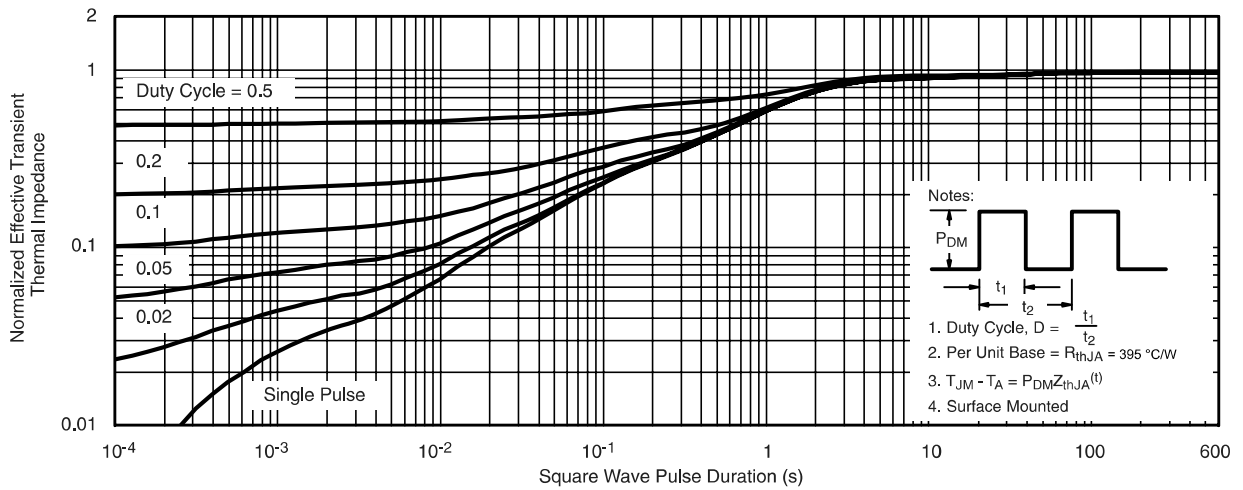
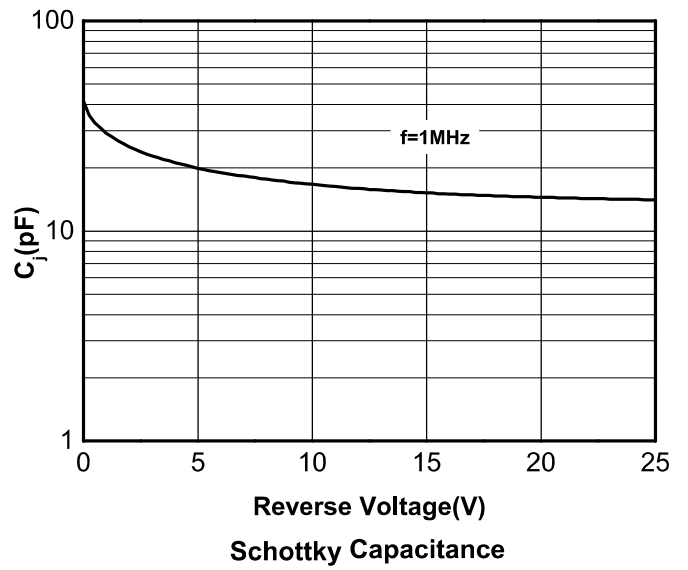
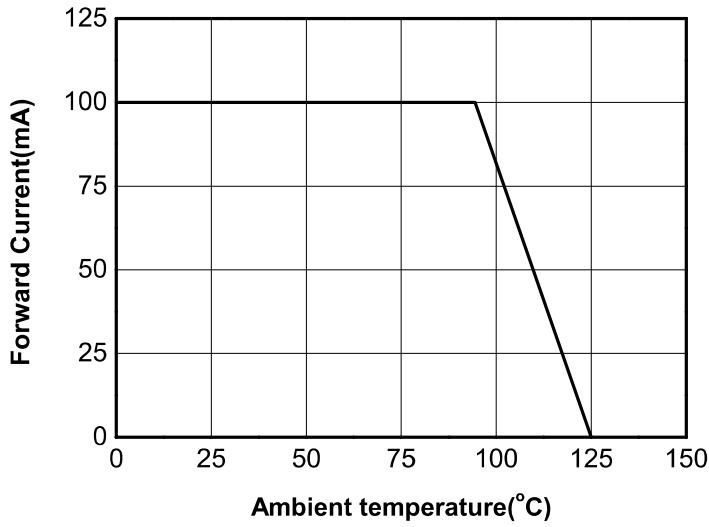
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 16V, V_{GS} = 0V$			1	μA
Gate-to-source Leakage Current	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 10V$			± 5	μA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	0.45	0.70	1.0	V
Forward Transconductance	g_{FS}	$V_{DS} = 10V, I_D = 0.35A$		1.0		S
Drain-to-source On-resistance ^{b, c}	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 0.55A$		380	550	m Ω
		$V_{GS} = 2.5V, I_D = 0.20A$		520	700	
		$V_{GS} = 1.8V, I_D = 0.20A$		735	1200	
CAPACITANCES, CHARGES						
Input Capacitance	C_{ISS}	$V_{GS} = 0V,$		30		pF
Output Capacitance	C_{OSS}	$f = 1MHz,$		7		
Reverse Transfer Capacitance	C_{RSS}	$V_{DS} = 10V$		5		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 4.5V,$ $V_{DS} = 10V,$ $I_D = 0.54A$		1.07		nC
Threshold Gate Charge	$Q_{G(TH)}$			0.12		
Gate-to-Source Charge	Q_{GS}			0.32		
Gate-to-Drain Charge	Q_{GD}			0.14		
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	$t_d(ON)$	$V_{GS} = 4.5V,$		7.2		ns
Rise Time	t_r	$V_{DD} = 10V,$		9.5		
Turn-Off Delay Time	$t_d(OFF)$	$I_D = 0.54A,$		19.6		
Fall Time	t_f	$R_G = 6\Omega$		4.6		
BODY DIODE CHARACTERISTICS						
Forward Voltage	V_{SD}	$V_{GS} = 0V, I_S = 0.3A$		0.85	1.5	V

SCHOTTKY BARRIER DIODE CHARACTERISTICS

Reverse Breakdown Voltage	V_R	$I_R = 100\mu A$	30			V
Forward Voltage	V_F	$I_F = 10mA$		0.28	0.35	V
		$I_F = 100mA$		0.37	0.42	V
Reverse Current	I_R	$V_R = 10V$		1.5	6	μA
		$V_R = 30V$		3.0	15	μA
Diode Capacitance	C_D	$V_R = 5V, F = 1MHz$		21		pF

Typical Characteristics (Ta=25°C, unless otherwise noted)

Output Characteristics

Transfer Characteristics

On Resistance vs. Drain Current

On Resistance vs. Gate-to-Source Voltage

On Resistance vs. Junction Temperature

Threshold Voltage vs. Temperature


Capacitance

Body Diode Forward Voltage

Gate Charge Characteristics

Safe Operating Power

Schottky Diode Forward current

Schottky Diode Reverse current



Transient thermal response (Junction-to-Ambient)

Package outline dimensions
SOT-563B
